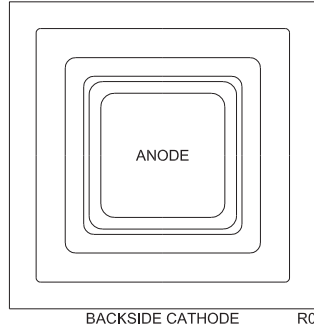


CPD89V-CMPD1001

Schottky Diode Die

0.25 Amp, 90 Volt

The CPD89V-CMPD1001 is a silicon switching diode designed for applications requiring high current capability.



MECHANICAL SPECIFICATIONS:

Die Size	12.8 x 12.8 MILS
Die Thickness	7.1 MILS
Anode Bonding Pad Size	5.1 x 5.1 MILS
Top Side Metalization	Al – 30,000Å
Back Side Metalization	Au-As – 10,000Å
Scribe Alley Width	2.36 MILS
Wafer Diameter	5 INCHES
Gross Die Per Wafer	103,344

MAXIMUM RATINGS: (T_A=25°C)

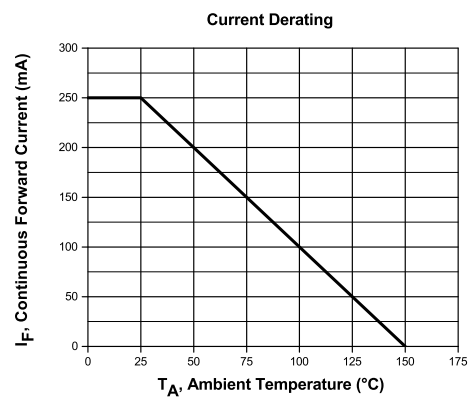
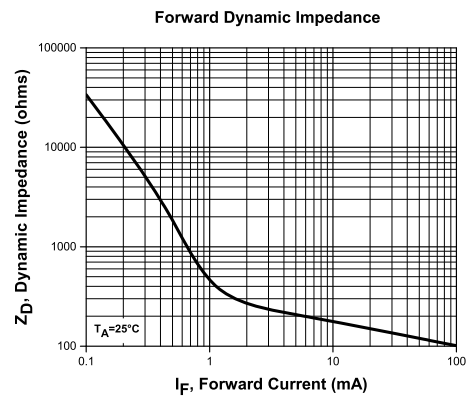
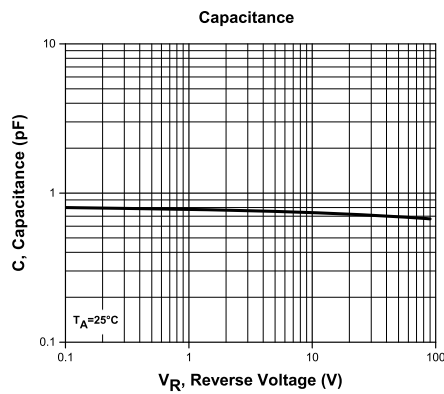
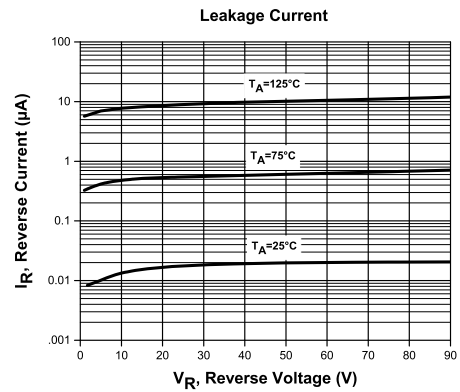
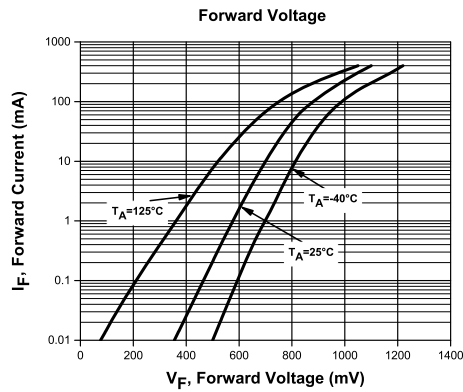
	SYMBOL		UNITS
Continuous Reverse Voltage	V _R	90	V
Continuous Forward Current	I _F	250	mA
Peak Repetitive Forward Current	I _{FRM}	600	mA
Peak Repetitive Reverse Current	I _{RRM}	600	mA
Peak Forward Surge Current, t _p =1.0μs	I _{FSM}	6.0	A
Peak Forward Surge Current, t _p =1.0s	I _{FSM}	1.0	A
Operating and Storage Junction Temperature	T _J , T _{stg}	-65 to +150	°C

ELECTRICAL CHARACTERISTICS: (T_A=25°C unless otherwise noted)

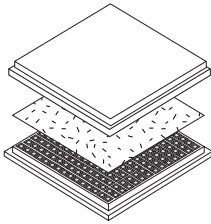
SYMBOL	TEST CONDITIONS	MIN	MAX	UNITS
I _R	V _R =90V		100	nA
BV _R	I _R =100μA	90		V
V _F	I _F =10mA		0.75	V
V _F	I _F =50mA		0.84	V
V _F	I _F =100mA		0.90	V
V _F	I _F =200mA		1.00	V
V _F	I _F =400mA		1.25	V
C _J	V _R =0, f=1.0MHz		35	pF
t _{rr}	I _R =I _F =30mA, I _{rr} =3.0mA, R _L =100Ω		50	ns

CPD89V-CMPD1001

Typical Electrical Characteristics



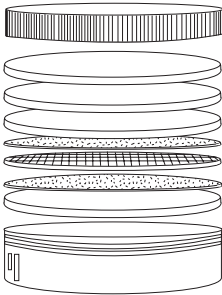
BARE DIE PACKING OPTIONS



BARE DIE IN TRAY (WAFFLE) PACK

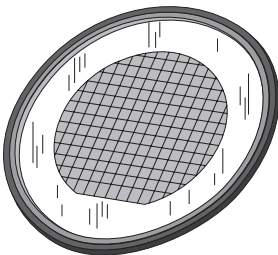
CT: Singulated die in tray (waffle) pack.
(example: CP211-PART NUMBER-CT)

CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes).
(example: CP211-PART NUMBER-CM)



UNSAWN WAFER

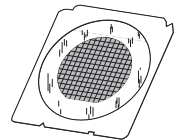
WN: Full wafer, unsawn, 100% tested with reject die inked.
(example: CP211-PART NUMBER-WN)



SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring,
100% tested with reject die inked.
(example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications:
www.centrasemi.com/bdspecs

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

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